General Description

The MAX19000 is a fully integrated, dual-channel, highperformance pin-electronics driver/comparator/load (DCL) with built-in level setters, and is ideal for memory and SOC ATE systems. Each MAX19000 channel includes a three-level pin driver, a window comparator, dynamic clamps, an active load, programmable cableloss compensation, and built-in programmable level setters.

The driver features a wide -2V to +6V operating range and a data rate of 1200Mbps at +2V operation. The driver includes high impedance, active termination (3rd-level drive), and is highly linear even at low-voltage swings. The window comparators provide extremely low timing variation with changes in slew rate, common mode, pulse width, and overdrive. The active load has an extended IOH and IOL current range, providing up to 20mA. The dynamic clamps provide damping of high-speed DUT waveforms when the DCL is in high-impedance receive mode. A serial interface configures the device, easing PCB signal routing.

The MAX19000 is available in a 64-pin TQFP package with an exposed pad.

Applications

Memory Testers SOC Testers

Features

Ordering Information/Selector Guide

+Denotes a lead(Pb)-free/RoHS-compliant package.

*EP = Exposed pad.

 $T = \text{Tape}$ and reel.

- ◆ High Speed: 1200Mbps at +2V Operation
- ◆ Fast Rise/Fall Times: 400ps Maximum at +2V (20% to 80%)
- ♦ Extremely Low Power Dissipation: 1.3W/Channel
- ◆ Wide, High-Speed Voltage Range: -2V to +6V
- ◆ Low-Leakage Mode: 10nA Maximum
- \triangleq Integrated Termination On the Fly (3rd-Level Drive)
- ♦ Programmable Cable-Loss Compensation (Drive and Receive)
- ♦ 20mA Active Load
- ◆ Digital Slew-Rate Control
- ♦ Integrated Voltage Clamps
- ♦ Integrated Level Setters
- ◆ Adjustable Output Resistance
- ◆ Adjustable Comparator Hysteresis
- ♦ Very Low Timing Dispersion
- ◆ Serial-Control Interface
- ◆ Minimal External Component Count

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For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

PACKAGE THERMAL CHARACTERISTICS (Note 1)

64 TQFP-EP Junction-to-Ambient Thermal Resistance (0JA)40°C/W Junction-to-Case Thermal Resistance (BJC)1NC/W

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a fourlayer board. For detailed information on package thermal considerations, refer to **www.maxim-ic.com/thermal-tutorial**.

ELECTRICAL CHARACTERISTICS

 $(VCC = +9.25V, VEE = -5.25V, VDD = +3.3V, VDHV = +3V, VDLV = 0V, VDTV = +1.5V, VCHV = +2V, VCLV = +1V, VCPHV =$ +6.7V, VCPLV_ = -2.7V, VCOMV_ = +2.5V, VLDHV_ = 0V, VLDLV_ = 0V, VCTV_ = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of \pm 15°C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

ELECTRICAL CHARACTERISTICS (continued)

 $(VCC = +9.25V, VEE = -5.25V, VDD = +3.3V, VDHV = +3V, VDLV = 0V, VDTV = +1.5V, VCHV = +2V, VCLV = +1V, VCPHV =$ $+6.7V$, V CPLV_ = -2.7V, V COMV_ = +2.5V, V LDHV_ = 0V, V LDLV_ = 0V, V CTV_ = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of $\pm 15^{\circ}$ C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +9.25V, V_{EE} = -5.25V, V_{DD} = +3.3V, V_{DHV_0} = +3V, V_{DLV_0} = 0V, V_{DTV_0} = +1.5V, V_{CHV_0} = +2V, V_{CLV_0} = +1V, V_{CPHV_0} = +1.5V, V_{CHV_0} = +1.5V, V_{CHV_1} = +1.5V, V_{CLV_1} = +1.5V, V_{CLV_2} = +1.5V, V_{CLV_1} = +1.5V, V_{CLV_2} = +1.5V, V_{CLV_1} = +1.5V, V_{CLV_2} = +1.$ $+6.7V$, $VCPLV = -2.7V$, $VCOMV = +2.5V$, $VLDHV = 0V$, $VLDLV = 0V$, $VCTV = +1.2V$, $CDRP = 000b$, $RO = 1100b$, $HYST = 000b$, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of $\pm 15^{\circ}$ C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

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ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +9.25V, V_{EE} = -5.25V, V_{DD} = +3.3V, V_{DHV_0} = +3V, V_{DLV_1} = 0V, V_{DTV_2} = +1.5V, V_{CHV_2} = +2V, V_{CLV_2} = +1V, V_{CPHV_2} = +1.5V, V_{CHV_3} = +1.5V, V_{CHV_4} = +1.5V, V_{CLV_5} = +1.5V, V_{CLV_6} = +1.5V, V_{CLV_7} = +1.5V, V_{CLV_8} = +1.5V, V_{CLV_9} = +1.5V, V_{CLV_1} = +1.$ +6.7V, VCPLV_ = -2.7V, VCOMV_ = +2.5V, VLDHV_ = 0V, VLDLV_ = 0V, VCTV_ = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of \pm 15°C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

ELECTRICAL CHARACTERISTICS (continued)

 $(VCC = +9.25V, VEE = -5.25V, VDD = +3.3V, VDHV = +3V, VDLV = 0V, VDTV = +1.5V, VCHV = +2V, VCLV = +1V, VCPHV =$ $+6.7V$, $VCPLV = -2.7V$, $VCOMV = +2.5V$, $VLDHV = 0V$, $VLDLV = 0V$, $VCTV = +1.2V$, $CDRP = 000b$, $RO = 1100b$, $HYST = 000b$, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of $\pm 15^{\circ}$ C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

ELECTRICAL CHARACTERISTICS (continued)

 $(VCC = +9.25V, VEE = -5.25V, VDD = +3.3V, VDHV = +3V, VDLV = 0V, VDTV = +1.5V, VCHV = +2V, VCLV = +1V, VCPHV =$ $+6.7V$, V CPLV_ = -2.7V, V COMV_ = +2.5V, V LDHV_ = 0V, V LDLV_ = 0V, V CTV_ = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of $\pm 15^{\circ}$ C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

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ELECTRICAL CHARACTERISTICS (continued)

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ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +9.25V, V_{EE} = -5.25V, V_{DD} = +3.3V, V_{DHV} = +3V, V_{DLV} = 0V, V_{DTV} = +1.5V, V_{CHV} = +2V, V_{CLV} = +1V, V_{CPHV} = +1.5V, V_{CLV} = +1.5V, V$ $+6.7V$, V_{CPLV} = -2.7V, V_{COMV} = +2.5V, V_{LDHV} = 0V, V_{LDLV} = 0V, V_{CTV} = +1.2V, CDRP_{_} = 000b, RO = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of $\pm 15^{\circ}$ C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +9.25V, V_{EE} = -5.25V, V_{DD} = +3.3V, V_{DHV_0} = +3V, V_{DLV_0} = 0V, V_{DTV_0} = +1.5V, V_{CHV_0} = +2V, V_{CLV_0} = +1V, V_{CPHV_0} = +1.5V, V_{CHV_0} = +1.5V, V_{CHV_0} = +1.5V, V_{CLV_0} = +1.$ $+6.7V$, V CPLV_ = -2.7V, V COMV_ = +2.5V, V LDHV_ = 0V, V LDLV_ = 0V, V CTV_ = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of \pm 15°C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +9.25V, V_{EE} = -5.25V, V_{DD} = +3.3V, V_{DHV} = +3V, V_{DLV} = 0V, V_{DTV} = +1.5V, V_{CHV} = +2V, V_{CLV} = +1V, V_{CPHV} = +1.5V, V_{CLV} = +1.5V, V$ $+6.7V$, VCPLV = -2.7V, VCOMV = +2.5V, VLDHV = 0V, VLDLV_ = 0V, VCTV = +1.2V, CDRP_ = 000b, RO = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of \pm 15°C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +9.25V, V_{EE} = -5.25V, V_{DD} = +3.3V, V_{DHV_0} = +3V, V_{DLV_1} = 0V, V_{DTV_2} = +1.5V, V_{CHV_2} = +2V, V_{CLV_2} = +1V, V_{CPHV_2} = +1.5V, V_{CHV_3} = +1.5V, V_{CHV_4} = +1.5V, V_{CHV_5} = +1.5V, V_{CHV_6} = +1.5V, V_{CHV_7} = +1.5V, V_{CHV_8} = +1.5V, V_{CHV_9} = +1.5V, V_{CHV_1} = +1.$ +6.7V, VCPLV_ = -2.7V, VCOMV_ = +2.5V, VLDHV_ = 0V, VLDLV_ = 0V, VCTV_ = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of ± 15 °C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

ELECTRICAL CHARACTERISTICS (continued)

 $(VCC = +9.25V, VEE = -5.25V, VDD = +3.3V, VDHV = +3V, VDLV = 0V, VDTV = +1.5V, VCHV = +2V, VCLV = +1V, VCPHV =$ +6.7V, VCPLV_ = -2.7V, VCOMV_ = +2.5V, VLDHV_ = 0V, VLDLV_ = 0V, VCTV_ = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of $\pm 15^{\circ}$ C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

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ELECTRICAL CHARACTERISTICS (continued)

 $(VCC = +9.25V, VEE = -5.25V, VDD = +3.3V, VDHV = +3V, VDLV = 0V, VDTV = +1.5V, VCHV = +2V, VCLV = +1V, VCPHV =$ +6.7V, VCPLV_ = -2.7V, VCOMV_ = +2.5V, VLDHV_ = 0V, VLDLV_ = 0V, VCTV_ = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at $T_J = +70^{\circ}$ C with an accuracy of $\pm 15^{\circ}$ C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

ELECTRICAL CHARACTERISTICS (continued)

 $(VCC = +9.25V, VEE = -5.25V, VDD = +3.3V, VDHV = +3V, VDLV = 0V, VDTV = +1.5V, VCHV = +2V, VCLV = +1V, VCPHV =$ $+6.7V$, VCPLV = -2.7V, VCOMV = +2.5V, VLDHV = 0V, VLDLV_ = 0V, VCTV = +1.2V, CDRP_ = 000b, RO = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70°C with an accuracy of $\pm 15^{\circ}$ C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

Note 2: V_{DHV}, V_{DLV}, and V_{DTV} levels are calibrated for gain at +0.125V and +3.875V and are calibrated for offset at +0.125V; relative to straight line between +0.125V and +3.875V.

Note 3: Change in level over operating range. Includes both gain and offset temperature effects. Simulated over entire operating range. Verified at worst-case points, which are at the endpoints VDHV - VDLV \geq 200mV.

Note 4: Guaranteed by design and characterization.

Note 5: DATA_ = H, VDHV_ = +3V, VDLV_ = 0V, VDTV_ = +1.5V, IOUT = ± 30 mA. Nominal target value is 48Ω .

Note 6: Resistance measurements are made using ± 2.5 mA current changes in the loading instrument about the noted value. Absolute value of the difference in measured resistance over the specified range is tested separately for each current polarity. Test conditions are at $I_{\text{DUT}} = \pm 1 \text{mA}$, $\pm 12 \text{mA}$, and $\pm 40 \text{mA}$, respectively.

Note 7: Rise time of the differential inputs DATA and RCV is 150ps (10% to 90%). SC1 = SC0 = 0, 40MHz, unless otherwise noted.

Note 8: Current supplied for a minimum of 10ns. Verified to be greater than or equal to the DC drive current by design and characterization.

Note 9: $V_{\text{DTV}} = +1V$, Rs = 50 Ω . External signal driven into T-line to produce a 0 to +2V edge at the comparator input with a 250ps rise time (10% to 90%). Measurement point is at comparator input.

Note 10: Measured from the 90% point of the driver output (relative to its final value) to the waveform settling to within the specified limit.

Note 11: Propagation delays are measured from the crossing point of the differential input signals to the 50% point of expected output swing.

Note 12: Average of the two measurements for propagation delay, data to output (t_{LH} and t_{HL}).

Note 13: Average of the four measurements in propagation delay, drive to high-Z, and high-Z to drive (tLZ, tHZ, tZL, tZH). Measured from crossing point of RCV_/NRCV_ to 50% point of the output waveform.

Note 14: Four measurements are made: V_{DHV_} to high-Z, V_{DLV_} to high-Z, high-Z to V_{DHV_}, and high-Z to V_{DLV_} (t_{LZ}, t_{HZ,} t_{ZL}, tz_H). The worst-case difference is reported.

Note 15: Average of the four measurements in propagation delay, drive to term, and term to drive $(t_{LT}, t_{HT}, t_{TL}, t_{TH})$. Measured from crossing point of RCV_/NRCV_ to 50% point of the output waveform.

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +9.25V, V_{EE} = -5.25V, V_{DD} = +3.3V, V_{DHV_{-}} = +3V, V_{DLV_{-}} = 0V, V_{DTV_{-}} = +1.5V, V_{CHV_{-}} = +2V, V_{CLV_{-}} = +1V, V_{CPHV_{-}} = +1V, V_{CPHV_{-}} = +1.5V, V_{CLV_{-}} = +1.5V$ +6.7V, VCPLV_ = -2.7V, VCOMV_ = +2.5V, VLDHV_ = 0V, VLDLV_ = 0V, VCTV_ = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ = 00b, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included. The device is tested at T_J = +70 \degree C with an accuracy of $\pm 15\degree$ C; specification compliance with supply and temperature variations are verified by guardbanding mean shifts of characterized data, unless otherwise noted. Temperature coefficients are measured at $T_J = +40^{\circ}C$ and $+100^{\circ}C$, unless otherwise noted.)

- Note 16: Four measurements are made: V_{DHV_} to V_{DTV_}, V_{DLV_} to V_{DTV_}, V_{DTV_} to V_{DHV_}, and V_{DTV_} to V_{DLV_} (t_{LT}, t_{HT,} t_{TL}, t_H). The worst-case difference is reported.
- Note 17: Cable-droop compensation disabled. Measured as close to DUT_ as possible using a high-bandwidth cable.
- Note 18: Cable-droop compensation enabled. Measured at the end of a 2m RG174 cable.
- Note 19: At this pulse width, the output reaches at least 95% of its nominal (DC) amplitude. The pulse width is measured at the DATA (input) pins.
- Note 20: Maximum data rate in transitions/second. A waveform that reaches at least 95% of its programmed amplitude can be generated at one-half of this frequency.
- Note 21: This specification is indicative of switching speed from VDHV_ or VDLV_ to VDTV_ and VDTV_ to VDHV_ or VDLV_ when VDLV_ < VDTV < VDHV. If VDTV < VDLV or VDTV > VDHV, the switching speed is degraded by roughly a factor of 3.
- Note 22: Both high and low comparators are tested for all tests.
- Note 23: Measured by using a servo to locate comparator thresholds.
- Note 24: Change in offset at any voltage over operating range. Includes both gain (CMRR) and offset temperature effects. Simulated over entire operating range. Verified at worst-case points, which are at the endpoints.
- Note 25: Change in offset voltage over input range.
- Note 26: V_{CHV_} and V_{CLV_} levels are calibrated for gain at +0.125V and +3.875V and are calibrated for offset at +2V. Relative to straight line between +0.125V and +3.875V.
- Note 27: Change in offset voltage with power supplies independently varied over their full range. Both high and low comparators are tested.
- **Note 28:** All propagation delays are measured from the V_{DUT} crossing to the differential output crossing.
- Note 29: Characterization is done with 50 Ω to ground at the end of a transmission line with a round-trip delay greater than 4ns.
- Note 30: 40MHz, 0 to +1V input to comparator, V_{CX} reference = +0.5V, 50% duty cycle, 250ps rise/fall time, $Z_{\rm S}$ = 50 Ω , Driver in term mode with V_{DTV} = +0.5V, unless otherwise noted. Hysteresis is disabled.
- Note 31: Input rise/fall time = 150ps. Cable-droop compensation disabled.
- Note 32: Input rise/fall time = 150ps. Cable-droop compensation enabled. Signal applied at beginning of 2m RG174 cable with compensation tuned for the cable.
- Note 33: Input rise/fall time = 150ps. Cable-droop compensation enabled. Signal applied at beginning of 2m RG174 cable with compensation tuned for the cable. Tested with both +1V and +5V input swings.
- Note 34: At this pulse width, the output reaches at least 90% of its nominal peak-to-peak swing. The pulse width is measured at the crossing points of the differential outputs. 250ps rise/fall time.
- **Note 35:** V_{DUT} = 200mVp-p, rise/fall time = 150ps, overdrive = 100mV, V_{DTV} = V_{CM}.
- Note 36: Input rise/fall time = 250ps. Cable-droop compensation disabled.
- Note 37: Input to comparator is 40MHz at 0 to +1V, 50% duty cycle, 1ns rise/fall time.
- Note 38: Unless otherwise noted, comparator outputs are terminated with 50Ω to +1.2V and CTV_ = +1.2V.
- Note 39: The min/max value of CTV_ specifications are guaranteed by simulation.
- Note 40: This specification is implicitly tested by meeting the high-impedance leakage specification I_{DUT} (VCLV_ = VCHV_ = +6V, $V_{DUT_{-}} = +2V$), and $I_{DUT_{-}}$ (V_{CLV₋ = V_{CHV₋ = -2V, V_{DUT₋ = +6V).}}}
- Note 41: Change in level over operating range. Includes both gain and offset temperature effects. Simulated over entire operating range. Verified at worst-case points.
- Note 42: Resistance measurements are made using ± 2.5 mA current changes in the loading instrument about the noted value Absolute value of the difference in measured resistance over the specified range, tested separately for each current polarity.
- Note 43: Ripple in the DUT_ signal after one round-trip delay. Stimulus is 0 to +3V, +2.5V/ns square wave from far end of 3ns transmission line with $R_S = 25\Omega$, clamps set to 0 and +3V.
- Note 44: Verified by dead-band test.
- Note 45: Typical values are at $V_{CC} = +9.25V$, $V_{FE} = -5.25V$. Production tests are performed with worst-case supply conditions for each specification. Supply conditions are either min V_{CC} and max V_{EE} , or max V_{CC} and min V_{EE} . Some tests may require both conditions.
- Note 46: Increasing DGS beyond 0V requires a proportional increase in the minimum supply levels. Specified ranges for all levels except VLDHV_, VLDLV_ are defined with respect to DGS.

Typical Operating Characteristics

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 $(VCC = +9.25V, VEE = -5.25V, VDD = +3.3V, VDW = +3V, VDU = 0V, VDTV = +1.5V, VCHV = +2V, VCLV = +1V, VCPHV = +6.7V, VQU = 0V, VUV = 0V, V$ $VCPU_ = -2.7V$, $VCOMM_ = +2.5V$, $VLDHV_ = 0V$, $VLDLV_ = 0V$, $VCTV_ = +1.2V$, $CDRP_ = 000b$, $RO_ = 1100b$, $HYST_ = 000b$, $SC_ = 000b$ $= 00b$, V_{DGS} = V_{GND} = V_{GNDDAC} = 0V, specifications apply after calibration, level-setter errors included, T_J = +70^oC, temperature coefficients are measured at $T_J = +40^{\circ}C$ to $+100^{\circ}C$, unless otherwise noted.)

Typical Operating Characteristics (continued)

 $(V_{CC} = +9.25V, V_{EE} = -5.25V, V_{DD} = +3.3V, V_{DHV} = +3V, V_{DLV} = 0V, V_{DTV} = +1.5V, V_{CHV} = +2V, V_{CLV} = +1V, V_{CPHV} = +6.7V, V_{CLV} = +1V, V_{CPHV} = +6.7V, V_{CLV} = +1V, V_{CPHV} = +6.7V, V_{CLV} = +1V, V_{CPHV} = +1.5V, V_{CLV} = +$ V_{CPLV} = -2.7V, V_{COMV} = +2.5V, V_{LDHV} = 0V, V_{LDLV_} = 0V, V_{CTV_} = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ $= 00b$, VDGS = VGND = VGNDDAC = 0V, specifications apply after calibration, level-setter errors included, T_J = +70°C, temperature coefficients are measured at $T_{\text{J}} = +40^{\circ}$ C to $+100^{\circ}$ C, unless otherwise noted.)

 $(V_{CC} = +9.25V, V_{EE} = -5.25V, V_{DD} = +3.3V, V_{DHV_0} = +3V, V_{DLV_0} = 0V, V_{DTV_0} = +1.5V, V_{CHV_0} = +2V, V_{CLV_0} = +1V, V_{CPHV_0} = +6.7V, V_{CLV_0} = +1V, V$ $VCPU_ = -2.7V$, $VCOMM_ = +2.5V$, $VLDHV_ = 0V$, $VLDLV_ = 0V$, $VCTV_ = +1.2V$, $CDRP_ = 000b$, $RO_ = 1100b$, $HYST_ = 000b$, $SC_ = 000b$ = 00b, V_{DGS} = V_{GND} = V_{GNDDAC} = 0V, specifications apply after calibration, level-setter errors included, T_{J} = +70^oC, temperature coefficients are measured at $T_J = +40^{\circ}C$ to $+100^{\circ}C$, unless otherwise noted.)

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Typical Operating Characteristics (continued)

 $(V_{CC} = +9.25V, V_{EE} = -5.25V, V_{DD} = +3.3V, V_{DHV} = +3V, V_{DLV} = 0V, V_{DTV} = +1.5V, V_{CHV} = +2V, V_{CLV} = +1V, V_{CPHV} = +6.7V, V_{CLV} = +1.5V, V$ $VCPU_ = -2.7V$, $VCOMM_ = +2.5V$, $VLDHV_ = 0V$, $VLDLV_ = 0V$, $VCTV_ = +1.2V$, $CDRP_ = 000b$, $RO_ = 1100b$, $HYST_ = 000b$, $SC_ = 000b$ $= 00b$, V_{DGS} = V_{GND} = V_{GNDDAC} = 0V, specifications apply after calibration, level-setter errors included, T_J = +70°C, temperature coefficients are measured at $T_J = +40^{\circ}C$ to $+100^{\circ}C$, unless otherwise noted.)

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Typical Operating Characteristics (continued)

 $(VCC = +9.25V, VEE = -5.25V, VDD = +3.3V, VDHV_ = +3V, VDLV_ = 0V, VDTV_ = +1.5V, VCHV_ = +2V, VCLV_ = +1V, VCPHV_ = +6.7V, VCLV_ = +1V, VCLV_ = +1$ V_{CPLV} = -2.7V, V_{COMV} = +2.5V, V_{LDHV} = 0V, V_{LDLV} = 0V, V_{CTV} = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ $= 00b$, V_{DGS} = V_{GND} = V_{GNDDAC} = 0V, specifications apply after calibration, level-setter errors included, T_J = +70°C, temperature coefficients are measured at $T_J = +40^{\circ}C$ to $+100^{\circ}C$, unless otherwise noted.)

VDUT_ = VDTV_ = +1.5V, CHV_ = CLV_ = 0, DRIVER TERM MODE, NO LOAD.

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Typical Operating Characteristics (continued)

 $(VCC = +9.25V, VEE = -5.25V, VDD = +3.3V, VDHV = +3V, VDLV = 0V, VDTV = +1.5V, VCHV = +2V, VCLV = +1V, VCPHV = +6.7V,$ V_{CPLV} = -2.7V, VCOMV = +2.5V, VLDHV = 0V, V_{LDLV} = 0V, V_{CTV} = +1.2V, CDRP_ = 000b, RO_ = 1100b, HYST_ = 000b, SC_ $= 00b$, V_{DGS} = V_{GND} = V_{GNDDAC} = 0V, specifications apply after calibration, level-setter errors included, T_J = +70°C, temperature coefficients are measured at $T_J = +40^{\circ}C$ to $+100^{\circ}C$, unless otherwise noted.)

MAX19000 Pin Configuration Veed Sensies van die Sensies
Dutte Gebeure van die Sensiese van die Sen
Verwys van die Sensiese van die Sensiese van die Sensiese van die Sensiese van die TOP VIEW GND 48| |47| |46| |45| |44| |43| |42| |41| |40| |39| |38| |37| |36| |35| |34| |33 47 | |46 | |45 | |44 | |43 | |42 | |41 | |40 | |39 | |38 VEE 49 32 V_{EE} V_{EE} (49) V_{EE} 31 CH1 CH0 50 **NCHO** 51 30 NCH₁ $CTV0$ 52 29 CTV1 CLO 53 28 CL1 **NCLO** 54 27 NCL1 GND $\sqrt{55}$ $\overline{26}$ GND **MAXIMI** GND $\sqrt{56}$ $\overline{25}$ GND MAX19000 24 RCV1 **RCV0** 57 NRCV0⁵⁸ 23 NRCV1 GND 59 22 GND $DATA0$ 60 21 DATA1 20 NDATA1 NDATA0 61 EP* LLEAKPO₆₂ 19 LLEAKP1 18 OVALARM TALARM 63 + VEE 64 17 V_{EE} 12 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 FORDACH
GND SCLUS CONDITION
BND SCLUS CONDITION
BND SCLUS CONDITION
HD SCLUS CONDITION
SCLUS CONDITION GND VCC e
S
S
S **TQFP** *EP = EXPOSED PAD ON PACKAGE TOP.

Pin Description

Pin Description (continued)

Figure 1. Simplified Block Diagram (only one of two channels is shown; the single serial interface controls both channels)

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Detailed Description

The MAX19000 dual-channel, pin-electronics DCL integrates multiple pin-electronics functions into a single IC. Each channel includes a three-level pin driver, a window comparator, dynamic clamps, an active load, and 10 independent 14-bit level-setting DACs. Additionally, each channel of the MAX19000 features programmable cable-droop compensation for the driver output and for the comparator input, adjustable driver output resistance, and driver slew-rate adjustment.

The MAX19000 driver features a wide -2V to +6V highspeed operating range, high-impedance and activetermination (3rd-level drive) modes, and is highly linear even at low voltage swings. The driver provides highspeed differential control inputs compatible with most high-speed logic families. The window comparators provide extremely low timing variation over changes in slew rate, pulse width, or overdrive voltage, and provide 50 Ω source outputs internally terminated to an applied voltage at CTV_. When high-impedance mode is selected, the programmable dynamic clamps provide damping of high-speed DUT_ waveforms. The 20mA active load facilitates fast contact testing when used in conjunction with the comparators, and functions as a pullup for opendrain/collector DUT_ outputs. Placing the MAX19000 DUT_ output into a very low-leakage state disables the DCL functions. This feature is convenient for making IDDQ measurements without the need for an output disconnect relay. Low-leakage control is independent for each channel. An SPI™-compatible serial interface and external inputs configure the MAX19000.

Integrated PE Mode Selection

The MAX19000 features two modes of operation, active and low leakage. The MAX19000 enters low-leakage mode when either LLEAKP_ is driven low or the LLEAKS bit is set to 1. Driving LLEAKP_ to 0 immediately forces the DCL to low leakage.

The serial bit LLEAKS $= 1$ can be used to force the DCL to low-leakage mode independent of other DCL control bits. Driving LLEAKS to 0 is necessary to allow any other mode of the DCL (Table 1).

Driver

The driver uses a high-speed multiplexer to select one of three DAC voltages (VDHV_, VDLV_, or VDTV_) or to select high-impedance mode. Multiplexer switching is controlled by high-speed differential inputs DATA_/ NDATA_ and RCV_/NRCV_ and mode-control bit TMSEL (see Table 2). The multiplexer output is buffered to drive DUT_. A programmable slew-rate circuit controls the

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slew rate of the buffer output.

In high-impedance mode, the clamps and comparators remain connected to DUT_, the DUT_ bias current is less than $\pm 2\mu$ A, and the node continues to track high-speed signals. In low-leakage mode, the bias current at DUT_ is further reduced to less than $\pm 10nA$, and signal tracking slows.

The nominal driver output resistance is 50 Ω and features an adjustment range of $\pm 2.5\Omega$ through the serial interface in 360m Ω increments.

Driver Slew-Rate Control

A slew-rate circuit controls the slew rate of the buffer output. Select one of four possible slew rates according to Table 3. The speed of the internal multiplexer sets the 100% driver slew rate (see the "Driver Large-Signal Response" graph in the *Typical Operating Characteristics* section). SC1 and SC0 are set to 0 at power-up or when RST is forced low.

Driver Cable-Droop Compensation

The driver incorporates programmable active cabledroop compensation. At high frequencies, transmission-Table 1. DCL Mode Control

Table 2. Driver Functional Overview

X = Don't care.

Table 3. Driver Slew-Rate Control

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line effects from the tester signal delivery path (PCB trace, connectors, and cabling between the MAX19000 DUT_ output and the device under test itself) can degrade the output waveform fidelity at the DUT_, resulting in a highly degraded or unusable signal. The compensation circuit reduces this degradation by adding a double time-constant decaying waveform to the nominal output waveform (preemphasis). Figure 2 depicts a comparison between a typical driver and the MAX19000, and shows how droop compensation counters signal degradation. There are long-time-constant control bits and short-timeconstant control bits in the DCL calibration registers to set the amount of compensation. Control bits CDRP_[2:0] vary the amplitude of the compensation signal. Table 4 shows the percent compensation as a function of control bit settings. The default power-on reset (POR) value is 000 for zero compensation.

Adjustable Driver Output Impedance $(\triangle R_O)$

The MAX19000 driver output impedance is adjustable to $\pm 2.5\Omega$ with a 360m Ω resolution. The RO bits in the DCL calibration register set the impedance value. Table 5 presents the output resistance control logic. The output resistance is set to R_O + 0.0Ω (0b1000) at power-up.

Driver Voltage Clamps

The voltage clamps (high and low) limit the voltage at DUT_ and suppress reflections when the channel is configured as a high-impedance receiver. The clamps behave as diodes connected to the outputs of highcurrent buffers (Figure 1). Internal circuitry compensates for the diode drop at 1mA clamp current. Set the clamp voltages using the level-setting DACs (CPHV_ and CPLV_). The driver clamps are enabled only when the driver is in the high-impedance mode. For transient suppression, set the clamp voltages to approximately the minimum and maximum expected DUT_ voltage range. The optimal clamp voltages are application-specific and must be empirically determined. Set the clamp voltages at a minimum of +0.7V outside the expected DUT_ voltage range when not using the clamps. Overvoltage protection then remains active without loading DUT_.

High-Speed Comparators

The MAX19000 provides two independent high-speed comparators for each channel. Each comparator has one input connected internally to DUT_ and the other input connected to either CHV_ or CLV_ (Figure 3). Cabledroop compensation is present on both channels. The comparators act as a high-speed window comparator. DAC voltages CHV and CLV control the comparator thresholds. Table 6 shows the truth table for the comparators. Figure 3 shows the comparator block diagram.

This configuration switches a 12mA current source between the two outputs, and each output provides an internal termination resistor connected to CTV_. These resistors are typically 50 Ω . Use alternate configurations to terminate different path impedance provided that the absolute maximum ratings are not exceeded. Note that the resistor value also sets the voltage swing. The output provides a nominal 300mVp-p swing with a 100 Ω differential load termination and a 50 Ω source termination. See the *Logic Outputs CH_, NCH_, CL_, NCL_* parameters in the *Electrical Characteristics* table for definition of the VOH voltage.

Table 4. Driver and Comparator Cable-Droop Compensation Control Logic

Table 5. Driver Delta RO Control

Figure 2. Driver/Comparator Cable-Droop Compensation

Table 6. Comparator Truth Table Table 7. Comparator Hysteresis Control

Figure 3. High-Speed Comparators Block Diagram

Comparator Hysteresis

The DCL register controls the high-speed comparator hysteresis. The HYST[2:0] bits of that register select one of eight values (0mV, 2mV, 4mV, 6mV, 8mV, 10mV, 12mV, or 15mV).

The HYST[2:0] bits are set to 0b000 at power-up or when $\overline{\text{RST}}$ is forced low. Table 7 shows the HYST[2:0] bit functions.

Comparator Cable-Droop Compensation

Comparator cable-droop compensation works the same as driver cable-droop compensation. See the *Driver Cable-Droop Compensation* section for a description.

Active Load

The active load is a linearly programmable current source and sink, a commutation buffer, and a diode bridge (Figure 4). Level-setting DACs LDHV_ and LDLV_ set the sink and source currents from 0mA to 20mA. Level-setting DAC COMV_ sets the commutation buffer output voltage. The source and sink naming convention is referenced to the MAX19000, so current out of the MAX19000 constitutes source current and current into the MAX19000 constitutes sink current.

The programmed source current loads the device under test when VDUT_ < VCOMV_. The programmed sink current loads the device under test when V_{DUT_} > V_{COMV_}. The high-speed differential inputs (RCV_/NRCV_) and three bits of the control word (LDDIS, LDCAL, and TMSEL) control the load. LLEAKP_ and LLEAKS place the load into low-leakage mode. The low-leakage controls override other controls. Table 8 details load control logic.

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Figure 4. Active Load Block Diagram (One Channel Shown)

X = Don't care.

**LEAK = LLEAKS + (*LLEAKP_*)*

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Load Calibration Enable (LDCAL)

LDCAL allows the load and driver to be simultaneously enabled for diagnostic purposes. LDDIS overrides LDCAL.

Serial Interface

An SPI-compatible serial interface controls the MAX19000. The serial interface, detailed in Figure 5, operates with clock speeds up to 50MHz and includes the \overline{CS} , SCLK, DIN, RST, LOAD, and DOUT signals. Serial-interface timing is shown in Figure 8 and timing specifications are detailed in the *Electrical Characteristics* table.

Loading Data Into the MAX19000

Load data into the 24-bit shift register from DIN on the rising edge of SCLK, while \overline{CS} is low (Figure 5). Enter the address and data bits in order from MSB to LSB. The MAX19000 is updated when the control and levelsetting data are latched into the control and level-setting registers. The control and level-setting registers are separated from the shift register by the input and channelselect registers. Two methods allow data to transfer from the shift register to the control and level-setting registers, depending on the state of external digital input LOAD.

Holding \overline{LOAD} high during the rising edge of \overline{CS} allows the shift register data to transfer only into the input and channelselect registers. Force LOAD low to transfer the data into the control and level-setting registers. Changes update on the falling edge of LOAD, which allows preloading of data and facilitates synchronizing updates across multiple devices.

Figure 5. Serial-Interface Block Diagram

Holding LOAD low during the rising edge of CS forces the input and channel-select registers to become transparent and all data transfers through these registers directly to the control and level-setting registers. Changes update on the rising edge of \overline{CS} . Figures 6 and 7 show how LOAD and CS function, and also the data configuration of SCLK, DIN, and DOUT. The calibration registers change on the rising edge of CS, regardless of the state of LOAD.

Serial-Port Timing

Timing and arrangement of the serial-port signals is shown in Figures 6, 7, and 8.

Serial-Interface DOUT

DOUT is a buffered version of the last bit in the serialinterface shift register. The complete contents of the shift register can be read at DOUT during the next write cycle. To shift data out without modifying any registers, perform a write with address bits $A4 = A5 = A6 = 1$. Use DOUT to daisy-chain multiple devices and/or to verify that data was properly shifted in during the previous write cycle.

Data is shifted in to the shift register on the rising edge of the SCLK, when $\overline{\text{CS}}$ is low. The shift register is 24 bits long.

Device Control

Control and level-setting registers are selected to receive data based on the channel and mode-select bits (A[7:0]). Tables 9 and 10 present the control register bits and functions. Level-setting DAC data and control register data are contained in the 16 data bits D[15:0]. Tables 9, 10, and 11 detail the bit functions. Clock in bit A7 first and bit D0 last, as shown in Figure 8.

Bit A7 allows access to the DAC calibration registers. Use the calibration registers to adjust the gain and offset of each DAC. Set bit A7 to write to the calibration registers. See the *Level-Setter DAC and Calibration Addresses* section for more information.

Table 9. Serial-Interface Control Bits

**Asserting the broadcast enable bit (A6) overrides the settings of bits A[5:4]; all channels are written to when bit A6 is set high.*

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Figure 6. Serial-Port Timing with Asynchronous Load

*Figure 7. Serial-Port Timing with Synchronous Load (*LOAD *Held Low)*

Figure 8. Detailed Serial-Port Timing Diagram

Level-Setter DAC and Calibration Addresses

The MAX19000 contains a total of 20 DACs to generate the DC voltage levels for the various control and monitor circuits of the 2-channel MAX19000, a total of 10 levels per channel. All DAC levels are set by a 14-bit code value that varies between a hex value of 0x0000 and 0x3FFF.

Table 12 identifies the serial-interface address of each DAC and the address of the associated calibration register. Registers can be addressed by individual channel or by utilizing a "broadcast address" that accesses both channels simultaneously. The level-setter output block diagram is shown in Figure 9.

Figure 9. Level-Setter Block Diagram

Level-Setter Calibration Registers (Gain and Offset Codes)

DAC calibration registers adjust the gain and offset of each DAC. Each DAC includes one calibration register. All DAC calibration registers are programmed with a 14 bit code (Table 10). The codes are divided into two fields, one field each for gain (GCAL_) and offset (OCAL_). All DACs provide a 6-bit field for gain and an 8-bit field for offset.

Calibration registers are reset to default values only during a POR. Asserting the RST does not force the calibration registers to default values.

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Table 11. Control and Calibration Register Bits

Table 12. DAC Addressing Table

Note 1: These values are reset during a POR or with the assertion of the $\overline{\text{RST}}$ pin.

Note 2: These values are reset during a POR only; thus, the device can be reset to a known state without requiring the reprogramming of calibration registers.

Level Transfer Functions

Each of the MAX19000 analog DAC levels is set with a transfer function that includes the 14-bit DAC code setting, the gain code setting, and the offset code setting. The V_{DAC} expression below presents the basic DAC transfer function. Each DAC provides a voltageoutput range of $-3V$ to $+7V$ (typ). All 20 of these DACs are identical and generate a voltage according to the following equation:

All DACs except VCOM_ DAC:

 $VDAC = 4 \times (DAC_code/16,384) \times VREF \times (1 - VG/VREF)$ $x (0.98 + 0.02 x)$ gain code/32) - 3V + (0.1 x offset $code/128 - 0.1) + VDGS + 1.2 \times VG$

where $VG = VGNDDAC - VDGS$.

VCOM_ DAC:

 $V_{\text{DAC}} = 4 \times (\text{DAC_code}/16,384) \times V_{\text{REF}} \times (1 - V_{\text{G}}/V_{\text{REF}})$ $x (0.995 + 0.02 x)$ gain code/32) - 3V + (0.1 x offset $code/128 - 0.1) + VDGS + 1.2 \times VG$

where $VG = VGNDDAC - VDGS$.

For all DACs, the offset code is an integer value between 0 and 255, and the gain code is an integer value between 0 and 63. Offset and gain codes are based on the calibration register settings (Table 13).

The error of the +2.5V external reference impacts the accuracy of the DAC levels; a 1% error in the +2.5V reference translates to a 1% error in the DAC level gain. A precision voltage reference such as the MAX6225 is recommended. The +2.5V external reference must be generated with respect to GNDDAC_. Care must be taken in making GND connections to the MAX19000 from the GND plane. There is a lot of current in each GND connection to the part; typically GND sources

Table 13. Level-Setter Transfer Functions

LEVEL	LEVEL-SETTER TRANSFER FUNCTION
VDHV	DAC voltage x V _{DHV_} gain + V _{DHV_} offset
VDLV	DAC voltage x V _{DLV_} gain + V _{DLV_} offset
VDTV	DAC voltage x VDTV_gain + VDTV_offset
VCHV	DAC voltage x VCHV_gain + VCHV_offset
VCLV	DAC voltage x V _{CLV} gain + V _{CLV} offset
VCPHV	DAC voltage x VCPHV_gain + VCPHV_offset
VCPLV	DAC voltage x VcPLV_gain + VcPLV_offset
VCOMV	DAC voltage x VCOMV_gain + VCOMV_offset
VLDHV [*]	(DAC voltage - VDGS) x (20mA/6V) x VLDHV gain + VLDHV offset
VLDLV_*	(DAC voltage - V _{DGS}) x (20mA/6V) x V _{LDLV} gain + VLDLV offset

**VLDHV_ and VLDLV_ levels below zero are truncated.*

approximately 90mA to the part, and this current demand can have significant AC components. The GNDDAC_ connection to the +2.5V reference and to all MAX19000 chips must also be carefully considered. A star connection should be made between GNDDAC_ and DGS. Voltage differences between GNDDAC_ and DGS should be minimized, as VG is equal to GNDDAC_ - DGS and is an error source for the DAC levels. See the *Level Transfer Functions* section for more information.

Calibration

After mathematically determining the calibration values, shown in Tables 14 and 15, the calibrated levels need to be checked and potentially adjusted up or down because the DAC gain and offset calibration registers have a nonlinear response that could result in the gain or offset values being off by as much as ± 3 LSBs, based on mathematical calculations from endpoint measurements during calibration.

Table 14. Offset Calibration Register

Table 15. Gain Calibration Register

Table 16. Calibration Points

Calibration Algorithm

The user can perform a system calibration by overwriting the default values in the gain and offset registers for any DAC level. The DAC calibration points are shown in Table 16.

The DAC calibration algorithm is as follows:

- 1) Set the offset DAC to midpoint $(1000 0000 = 0)$ nominal).
- 2) Set the level DAC to gain point 1 (GP1).
- 3) Set the gain DAC code to minimum = 00 0000.
- 4) Measure the output and call it VGAINMINGP1.
- 5) Set the gain DAC code to maximum = 11 1111.
- 6) Measure the output and call it VGAINMAXGP1.
- 7) Set the level DAC to gain point 2 (GP2).
- 8) Set the gain DAC code to minimum = 00 0000.
- 9) Measure the output and call it VGAINMINGP2.
- 10) Set the gain DAC code to maximum = 11 1111.
- 11) Measure the output and call it VGAINMAXGP2.
- 12) Calculate the gain code.

The DAC is not 0V based, so there are gain differences at 0V and at 3V.

For 63 codes, calculate the average range:

GAINMIN = (VGAINMINGP2 - VGAINMINGP1)/

(GP2 - GP1)

GAINMAX = (VGAINMAXGP2 - VGAINMAXGP1)/ (GP2 - GP1)

GAINRANGE = GAINMAX - GAINMIN LSB = GAINRANGE/63

Calculated gain code = (1 - GAINMIN)/LSB. Call it GCALC.

- 13) For gain DAC codes of GCALC 2 to GCALC + 2, measure the gain (VGP2 - VGP1)/(GP2 - GP1) at each code, where VGP_ is the output at level DAC code GP_.
- 14) From codes GCALC 2 to GCALC + 2, choose the code that yields a gain closest to 1.0 and program the gain DAC to that code.
- 15) Set the level DAC to the offset point (OP).
- 16) Set the offset DAC code to minimum = 0000 0000.
- 17) Measure the output and call it VOFFSMIN.
- 18) Set the offset DAC code to maximum = 1111 1111.
- 19) Measure the output and call it VOFFSMAX.
- 20) Calculate the offset code:

OFFSRANGE = VOFFSMAX - VOFFSMIN LSB = OFFSRANGE/255

Calculated offset $code = (OP - VOFFSMIN)/LSB$. Call it OCALC.

- 21) For offset DAC codes of OCALC 2 to OCALC + 2, measure the offset (VOP - OP) at each code, where VOP is the output at level DAC code OP.
- 22) From codes OCALC 2 to OCALC + 2, choose the code that yields an offset closest to the desired value and program the offset DAC to that code.
- 23) The DAC should now be calibrated.

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Calibration Example

The following is a calibration example for a DHV_ driver output high level:

- 1) With $DHV_ = +0.125V$, VGAINMINGP1 = $+0.1600V$ and V GAINMAXGP1 = $+0.084851V$.
- 2) With $DHV_ = +3.875V$, VGAINMINGP2 = $+3.8239V$ and V GAINMAXGP2 = $+3.9246V$.
- $GAINMIN = (3.8239V 0.1603V)/(3.875V 0.125V) =$ 0.976967.
- 4) GAINMAX = (3.9246V 0.084851V)/(3.875V 0.125V) $= 1.023933$.
- 5) GAINRANGE = 1.023933 0.976967 = 0.046966.
- 6) LSB = GAINRANGE/63 = 0.000745.
- 7) Gain code = $(1 0.976967)/0.000745 = 31$.
- 8) Remeasured +0.125V output at gain codes 29, 30, 31, 32, and 33 = +0.127601V, +0.127091V, +0.126848V, +0.126473V, and +0.126098V.
- 9) Remeasured +3.875V output at gain codes 29, 30, 31, 32, and 33 = +3.876120V, +3.876615V, +3.877110V, +3.877605V, and +3.878100V.
- 10) Gains at codes 29, 30, 31, 32, and 33 are +0.999605, +0.999837, +1.000070, +1.000302, and +1.000534.
- 11) Adjusted gain code $= 31$ (the closest to 1.0).
- 12) Program the gain DAC to code 31.
- 13) Set V_{DHV} = +0.125V, VOFFSMIN = +0.0269V, and $VOFFSMAX = +0.2180V$.
- 14) Calculate the offset code:

OFFSRANGE = VOFFSMAX - VOFFSMIN = +0.2180V - 0.0269V = +0.1911V.

 $LSB = OFFSRANGE/255 = +0.000749V$.

Calculated offset code = $(0.125V - V$ OFFSMIN) $LSB = 131.$

- 15) Offsets at codes 129, 130, 131, 132, and 133 are +0.1222V, +0.1230V, +0.1237V, +0.1245V, and +0.1252V.
- 16) Adjusted offset code = 133 (the closest to $+0.125V$).
- 17) Program adjusted offset code.
- 18) DHV should now be calibrated.

Applications

Device Power-Up State

Upon power-up, the DCL enters low-leakage mode; the DCL and calibration registers default to 0x0004 and 0x2080, respectively. See Table 12 for initial power-up values for the levels. Power supplies can be powered on in any sequence.

Alarms

The MAX19000 features two fault-condition alarms. The first is a temperature sense alarm that activates when the MAX19000 internal temperature exceeds $+125^{\circ}$ C. The second fault condition activates when the voltage on DUT_ falls outside programmable voltage levels, higher than VCPHV or below VCPLV. The VCPHV and VCPLV levels are set by internal 14-bit DACs and are shared between the high-impedance clamp circuits and OVALARM. Each alarm has an individual enable in the DCL register (channel 0 only) (see Table 10): EN_TEMP_ALARM and EN_OV_ALARM. A binary "1" must be programmed into these enable bits for the monitor circuits to assert their respective alarm outputs (TALARM and OVALARM). Alarm outputs are active low, open drain, and referenced to DGND. It is anticipated that the user implements the latch function in ASIC/ FPGA that monitors the TALARM signal. The MAX19000 OVALARM circuit shares its programmable DAC levels with the driver high-Z clamp circuits. The high-Z clamps can never be disabled. To eliminate their influence on the DUT_ line, one simply programs the high-Z clamp voltages out of the way. The proximity of the driver high-Z clamps to the OVALARM thresholds influences the behavior of the OVALARM operation. The OVALARM circuit positively triggers the OVALARM output when a fault condition due to a VOVH/VCPH threshold crossing can source at least 6mA of current to the clamp circuit. Fault conditions causing less than 6mA may or may not

VREF - VGNDDAC_ INTRODUCES GAIN ERROR IN DAC OUTPUT VOLTAGE EQUAL TO (V_{REF} - V_{GNDDAC_})/+2.5V. KEEP GND ERROR LESS THAN THE 20mV GAIN CALIBRATION RANGE.
KEEP THE GNDDAC_ - GND WITHIN ±100mV AND GNDDAC_ - DGND WITHIN ±100mV.

Figure 10. Sample Connection Diagram for Two Parts per Board

trigger an OVALARM output. The same is true near the VOVL/VCP threshold crossing for low voltages (i.e., the fault condition would have to sink at least 6mA of current to the clamp circuit). It should also be noted that when normal high-Z clamp operation is desired because of the lack of source termination at the DUT_, one should disable the OVALARM circuit to eliminate the possibility of nuisance tripping on the OVALARM output due to normal high-Z clamp operation.

Temp Sensor The temp-sensor function is enabled utilizing the TSMUX0

bit in the TS register. Contents of the TS register can be modified through the serial interface. Table 17 defines the bit code necessary to enable this function. The tempsensor output is an analog value.

DATA_ and RCV_ Inputs

DATA and RCV are terminated differentially with internal 100 Ω , as shown in Figure 11.

Power-Supply Considerations

Bypass each supply input to GND and REF to DGS with 0.1µF capacitors. Additionally, use bulk bypassing of at least 10µF where the power-supply connections meet the circuit board.

Exposed Pad

The exposed pad (EP) is internally connected to VEE. Connect EP to a large plane or heat sink to maximize thermal performance. EP is not intended as an electrical connection point. Leave EP electrically unconnected, or connect to VFF. Do not connect EP to ground.

Table 17. Temp-Sensor Output Control

Figure 11. DATA_ and RCV_ Terminations

Chip Information

PROCESS: BiCMOS

Package Information

For the latest package outline information and land patterns (footprints), go to **www.maxim-ic.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

MAX19000

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